

JAN 10 2001

Attorney's Docket No.: 1797226000000401  
1465-#

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Ohtani Art Unit : 1765  
Serial No.: 09/596,755 Examiner : Robert Kunemund  
Filed : June 15, 2000  
Title : MANUFACTURING METHOD OF SEMICONDUCTOR AND  
MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

Commissioner for Patents  
Washington, D.C. 20231

TRANSMITTAL LETTER AND PETITION FOR AUTOMATIC EXTENSION

Correspondence relating to this application is enclosed.  
The required fees are computed below. Please apply any charges  
not covered, or any credits, to Deposit Account No. 06-1050.

Total Claims	44	-	20	=	24	\$432
Independent	7	-	3	=	4	<u>\$320</u>
TOTAL FEE DUE						\$752

A check for \$752 is attached.

Respectfully submitted,

Date: 1/24/01

*JCH* Reg. No. 40,631  
For Scott C. Harris  
Reg. No. 32,030

Fish & Richardson P.C.  
PTO Customer No. 20985  
4350 La Jolla Village Drive, Suite 500  
San Diego, CA 92120  
Telephone: (858) 678-5076  
Facsimile: (858) 678-5099  
E-mail: [fri@fish.com](mailto:fri@fish.com)

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner of Patents, Washington, D.C. 20231.

Signature

*Susan Regan*

Using U.S. Postal FIM and Digital Signature Certification

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Ohtani                  Art Unit : 1765  
Serial No.: 09/596,755                  Examiner : Robert Kunemund  
Filed        : June 15, 2000  
Title        : MANUFACTURING METHOD OF SEMICONDUCTOR AND  
                  MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Official Action dated October 24, 2000, Paper No. 2, in the above-referenced application, please amend the above-identified application as follows.

In the Claims:

Please cancel claim 1 without prejudice.

Please add the following new claims.

2. (New) A method for manufacturing a semiconductor device comprising steps of:

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the

U.S. Patent and Trademark Office, Washington, D.C. 20231

Signature

Susan Regan

Customer Support Department, USPTO